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Diffusion barrier property of electroless Ni-W-P coating in high temperature Zn-5Al/Cu solder interconnects

Li Liu, Zhiwen Chen, Zhaoxia Zhou, Guang Chen, Fengshun Wu, Changqing Liu



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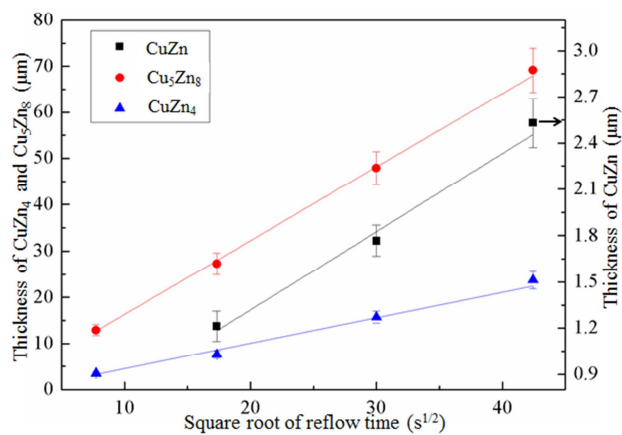
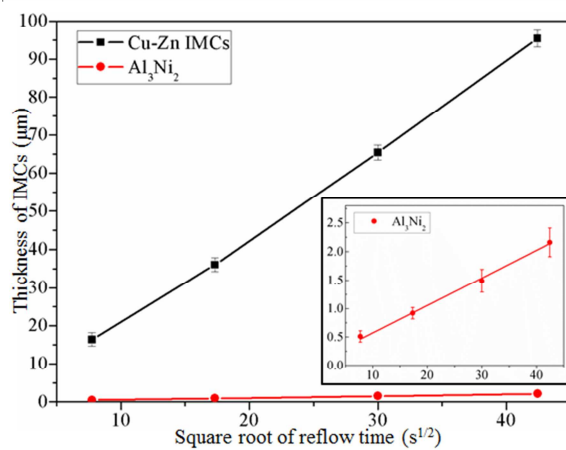
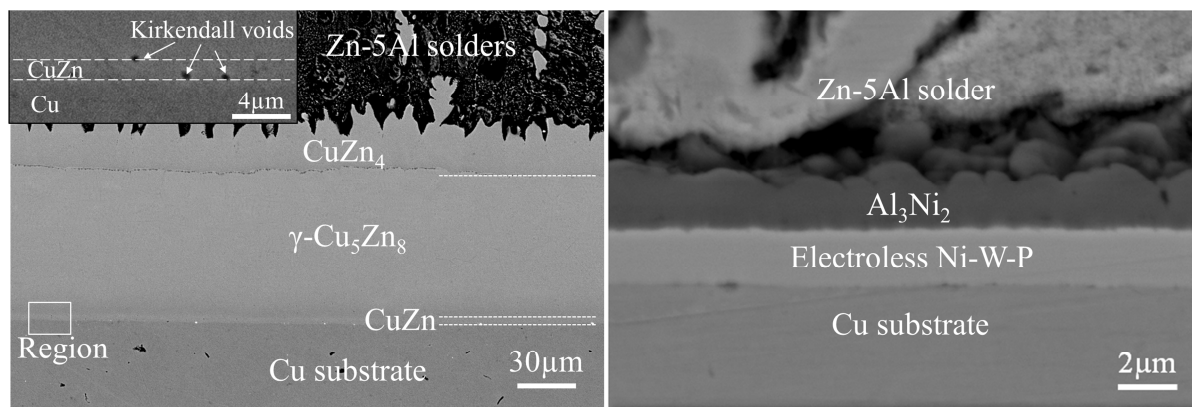
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